



HPC3000-IL

3U IP67 Dual-GPU Rugged Server with Intel

® Xeon Silver 4316 Processor



- Intel® 3rd Ice Lake Gen Xeon® Silver 4316(20xC) Processor
- 2TB NVMe Gen 4.0 (W/R,3000MB/sec)-System Drive
- 8xSATA Drive Bay (SAS/SATA) RAID10
- 4 x 100GbE , 2 x GbE
- 2 x Nvidia Quadro RTX A4000 GPU (6,144 CUDA)
- DC-DC 24V (800W)
- Options for Redundant AC 100~240V Input
- MIL-STD-810 Thermal, shock, vibration, Humidity EMI / EMC Resistance
- MIL-STD -461 24V~40V DC (optional)
- Extreme Temperature : -20 ~+55 degree



Specifications

System

CPU	Intel® Ice Lake Xeon™ Sliver 4316 150W (20 Core, 2.3GHz, Up to 3.4Ghz)
Memory type	Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz

Display

GPU	Dual x NVIDIA Quadro RTX A4000 PCI-E (16GB-GDDR6, CUDA 6,144)
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Storage

NVMe	2TB NVMe 4.0 M.2 (R/W, 3000MB/sec) Option : 2TB RAID1 NVMe 4.0 (R/W, 3000MB/sec)
HDD/SSD	8 x 2.5" Easy Swap HDD/SSD Tray RAID 10 Support

Ethernet

Ethernet	2 x Intel® I350-AM4 4x Intel 100GbE (SFP+) E810-CQDA2*2(Options)
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Front I/O

USB3.0	2 x DTL38999(USB3FTV7AZNF312)
100GbE	4 x DTL38999(LCFTV6MDGN)
GbE	2 x DTL38999(LCFTV6MDGN)
IPMI	1 x DTL38999(LCFTV6MDGN)
VGA	1 x DTL38999(TV07RW-9-09S)
COM	1 x DTL38999(TV07RW-9-09S)
DIO	1 x DTL38999(TV07RW-9-09S)
DC-IN	1 x DTL38999(PL082-300-20)
Power Button	1 x Power Button with LED backlight
SDD	1 x SSD light 8 x 2.5" Easy swap HDD/SSD Tray

Power Requirement

Power Input	DC-DC 24V (800W) Option 1 : Redundant AC 100~240V Input
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Option 2 : MIL-STD -461 24~40V DC-Input

Application

Application Military Platforms Requiring Compliance MIL-STD-810
Embedded Computing and applications subject to Harsh Temperature, Shock, Vibration, Attitude, Dust and EMI Conditions.

OS support list

Windows Windows 10

Linux By request

Environment

Dimension 480x112x500 mm (WxHxD)

Classis Aluminum Alloy, Corrosion Resistant

Operation Temp. -20 to +55°C

Storage Temp. -40 to +85°C

Relative Humidity 5% to 95%, non-condensing

EMC EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV
EN 61000-4-3: 10V/m
EN 61000-4-4: Signal and DC-Net: 1 kV
EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV
CE and FCC
MIL-STD-461 (Options):
CE102 basic curve, 10kHz - 30 MHz
RE102-4, (1.5 MHz) -30 MHz - 5 GHz
RS103, 1.5 MHz - 5 GHz, 50 V/m equal for all frequencies

MIL-STD-810 Method 500.5, Procedures I and II (Altitude, Operation):
12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia)
Method 500.5, Procedures III and IV (Altitude, Non-Operation):
15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia)
Method 501.5, Procedure I (Storage/High Temperature)
Method 501.5, Procedure II (Operation/High Temperature)
Method 502.5, Procedure I (Storage/Low Temperature)
Method 502.5, Procedure II (Operation/Low Temperature)
Method 503.5, Procedure I (Temperature shock)
Method 507.5, Procedure II (Temperature & Humidity)
Method 514.6, Vibration Category 24/Non-Operating (Category 20 &

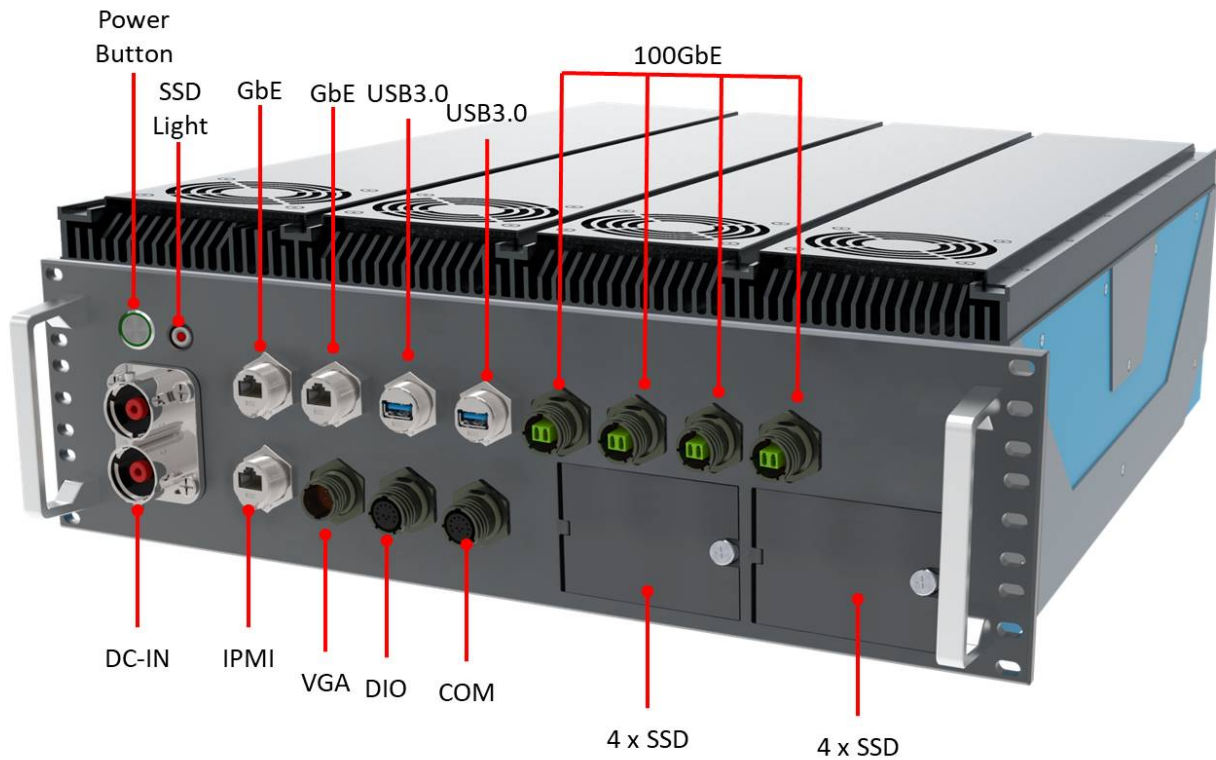
24,Vibration)

Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration)

Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock)

Method 516.6, Shock-Procedure I Operating (Mechanical Shock)

Front I/O



Ordering Information

Model	Description
HPC3000-IL-D	3U IP67 Conduction Cooled Rugged Dual-GPU Server platform supporting NVIDIA® QUADRO RTX4000 and Intel® Xeon® 4316 processor, 4 x 100GbE, 2 x GbE, 1 x IPMI, 1 x VGA, 1 x COM, 1 x DIO, DC-DC 24V, Operation Temp. -20 to +55°C
HPC3000-IL-A	3U IP67 Conduction Cooled Rugged Dual-GPU Server platform supporting NVIDIA® QUADRO RTX4000 and Intel® Xeon® 4316 processor, 4 x 100GbE, 2 x GbE, 1 x IPMI, 1 x VGA, 1 x COM, 1 x DIO, AC 100~240V, Operation Temp. -20 to +55°C
HPC3000-IL-M	3U IP67 Conduction Cooled Rugged Dual-GPU Server platform supporting NVIDIA® QUADRO RTX4000 and Intel® Xeon® 4316 processor, 4 x 100GbE, 2 x GbE, 1 x IPMI, 1 x VGA, 1 x COM, 1 x DIO, MIL-STD-461 DC-IN 24~40V, Operation Temp. -20 to +55°C